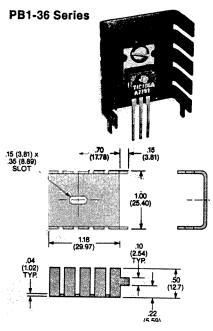
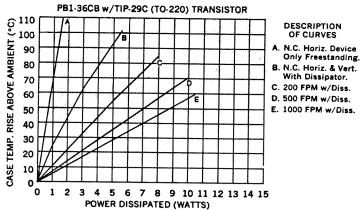
HEAT DISSIPATORS FOR PLASTIC CASE, CASE-MOUNTED SEMICONDUCTORS

Vertically mounted heat dissipators with board mounting tabs

- Permits higher power levels or lower operating temperatures while occupying a minimum of valuable board space.
- Allows back-to-back dual mounting for thermal matching applications.
- Bendable tabs simplify installation to the circuit board — no mounting hardware or special tools required.
- Dissipators are available with nickel or tin finishes — allows heat sink mount-
- ing tabs to be flow-soldered onto board along with other components.
- Each dissipator is optimally designed for maximum effective surface area in a minimum working envelope.



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.

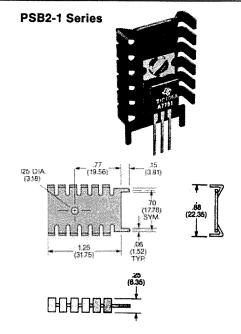


- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 2.4 °C/watt for unplated part in natural convection only.

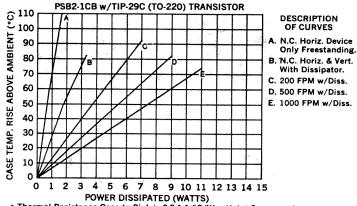
Ordering Information

	d Comm'l. Black Anodize	Mil. Black Anodize	Solderable Plating		Semiconductor	Max. Weight
Unplated			Nickel	Tin	Accommodated	(Grams)
PB1-36U	PB1-36CB	PB1-36B	PB1-36ND	PB1-36T	T0-126, T0-127, T0-220	3.9

Note: See page iv for other finishes.



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 3.5 °C/watt for unplated part in natural convection only.

Ordering Information

200	. Vin					
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Solderable Plating		Semiconductor	Max. Weight
			Nickel	Tin	Accommodated	(Grams)
PS82-1U	PSB2-1CB	PSB2-1B	PSB2-1ND	PSB2-1T	TO-126, TO-127, TO-220	2.4

Note: See page iv for other finishes.

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